IEC QUALITY ASSESSMENT SYSTEM (IECQ)
covering Electronic Components,
Assemblies, Related Materials and Processes
For rules and details of the IECQ visit www.iecq.org

Schedule of Scope to Certificate of Conformity

Approved Component - Capability

IECQ Certificate No.: IECQ-C BSI 13.0001

CB Certificate No.: 030/ICA

Schedule Number: IECQ-C BSI 13.0001-S **Rev No.:** 3 **Revision Date:** 2018/01/11 **Page** 1 **of** 2

Board Types:
Rigid Multilayer (Type 4) — IPC 6012C Class 3*

Rigid double-sided with plated through holes (Type 2)
Rigid single & double-sided with plain holes (Types 1 & 2)
Double-Sided boards (Type 2)
Single-Sided Boards (Type 1 & 2)

Flex-Rigid multilayer with through holes (Type 4) — IPC 6013B Class 3*

*With reduced sampling for structural integrity (micro-section) in accordance with IECQ OD 301

Base Materials:
Epoxide Woven Glass (IPC4101, 4202, 4203, BS4584)
Polyimide film/polyester film (IPC 4204)
Polytetrafluorethylene (IPC 4103)

Board Size:
495.30 mm x 419.10 mm single/double and multilayer
261.87 mm x 322.33 mm flex-rigid multilayer

Number of Layers:

32 maximum	Rigid multilayer
10 maximum	Flex-Rigid multilayer

Conductors:
0.050 mm (photomech) Tolerance -0.01+0.03mm
0.10 mm (photomech) Tolerance -0.02 +0.03 mm

Plated-through Hole Diameter:

0.20 mm	Minimum	Finished hole size
0.80 mm	Minimum	Finished hole size

Aspect Ratio:

20 : 1	Maximum	single and double sided
16.0:1	Maximum	multilayer
2.27 : 1	Maximum	flex-rigid multilayer

This schedule is only valid in conjunction with the referenced Certificate of Approval
This approval and any schedule(s) may only be reproduced in full.
This approval is not transferable and remains the property of the issuing body.
The Status and authenticity of this approval and any schedule(s) may be verified by visiting t
Official IECQ Website. www.iecq.org

BSI, Kitemark Court Davy Avenue Knowlhill Milton Keynes MK5 8PP UK

Schedule of Scope to Certificate of Conformity

Approved Component - Capability

IECQ Certificate No.: IECQ-C BSI 13.0001

CB Certificate No.: 030/ICA

Schedule Number: IECQ-C BSI 13.0001-S **Rev No.:** 3 **Revision Date:** 2018/01/11 **Page** 2 **of** 2

Finishes: * Hot Air Solder Levelling
Immersion Silver
2.5µm Gold over Copper Edge Contacts
Liquid Photopolymer Solder Resist
Legend; UV or Oven Cured
Solder resist UV cured

Additional: Selective Electroplated Gold (2.5 µm) on Copper
Selective Electroless Gold (0.05 µm) on Copper
Silver, Organic Coating
NemaL1-I

***** This finish meets the solderability requirements.

This schedule is only valid in conjunction with the referenced Certificate of Approval
This approval and any schedule(s) may only be reproduced in full.
This approval is not transferable and remains the property of the issuing body.
The Status and authenticity of this approval and any schedule(s) may be verified by visiting t
Official IECQ Website. www.iecq.org

BSI, Kitemark Court Davy Avenue Knowlhill Milton Keynes MK5 8PP UK